

DESIGN INFORMATION

BOARD SIZE: (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

4900ML

X

1000ML

Number of Layers : 2

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 30 MIL

MINIMUM ANNUAL RING 0.177mm (7MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: MAX +/- 5 MIL HOLES +/- 3 MIL

MATERIAL:

FR-408

FR-4 High Tg

X

OTHER

FR4

THICKNESS: 63 MIL (1.6mm) +/- 10%

TOLERANCE:

X

ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/-

BOW & TWIST:

X

ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: X 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)

INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DILLING:

REFERENCE: X AS SHOWN X NC\_DRILL FILES

PTH MIN COPPER THICKNESS: X 1MIL OTHER

BOARD FINISH:

SILKSCREEN: X TOP X BOTTOM

SILKSCREEN COLOR: X WHITE OTHER

SOLDER RESIST COLOR:

X GREEN

BLUE

OTHER

SURFACE FINISH: X IMMERSION GOLD (ENIG) ENERP

IMM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL:

CUT AND TRIM PER MECH LABEL 1

N.C. ROUTE X V. SCORE

CERTIFICATION: MATERIALS AND WORKSMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

X ANSI IPC-A-600F CLASS -> 1 X 2 X 3

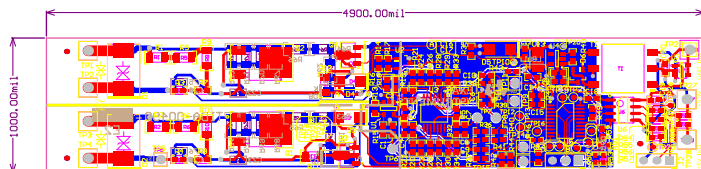
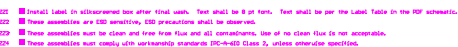
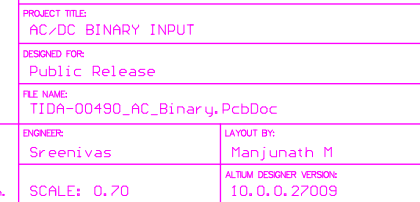
X UL 94V-0 X RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENCING: YES X NO

MICROSECTION: YES IMPEDANCE CONTROL: YES NO X

BARE BOARD ELEC. TEST: NONE X REQUIRED PER ORDER

MANUFACTURER'S UL: RAIL METAL X SILK



COMPONENTS MARKED "NIP" SHOULD NOT BE POPULATED. JSTANLDR 38 TOM CLONE "NO" CARRY OVERMOVED

ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #:	TID000490	REV:	E2	SUN REV: Not In Version Control
LAYER NAME = <u>Non-etchable</u> <u>2oz</u> <u>DM</u>		← 305401				
PLOT NAME = <u>Multi-Layer</u> <u>Composite Print</u>		GENERATED:	2/23/2015	2:46:18 PM	TEXAS INSTRUMENTS	

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